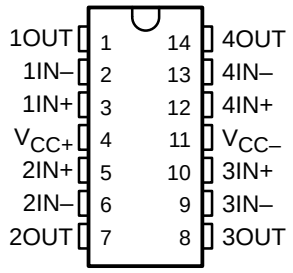
SLOS101C – FEBRUARY 1979 – REVISED FEBRUARY 2002

- **Wide Range of Supply Voltages, Single Supply . . . 3 V to 36 V or Dual Supplies**
- **Class AB Output Stage**
- **True Differential Input Stage**
- **Low Input Bias Current**
- **Internal Frequency Compensation**
- **Short-Circuit Protection**
- **Designed to Be Interchangeable With Motorola MC3303, MC3403**

MC3303 . . . D, N, OR PW PACKAGE
MC3403 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



description

The MC3303 and the MC3403 are quadruple operational amplifiers similar in performance to the μA741, but with several distinct advantages. They are designed to operate from a single supply over a range of voltages from 3 V to 36 V. Operation from split supplies also is possible, provided the difference between the two supplies is 3 V to 36 V. The common-mode input range includes the negative supply. Output range is from the negative supply to V_{CC} – 1.5 V. Quiescent supply currents are less than one-half those of the μA741.

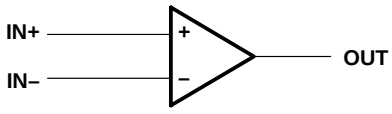
The MC3303 is characterized for operation from –40°C to 85°C, and the MC3403 is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

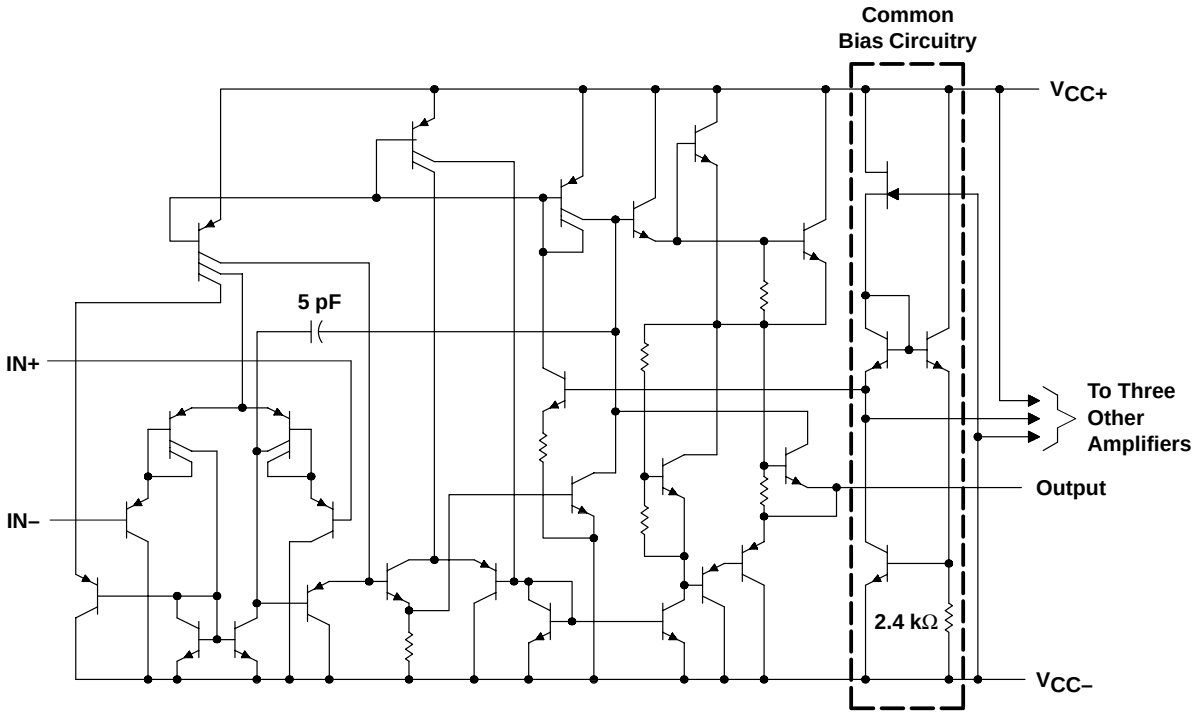
T_A	V_{IO}MAX AT 25°C	PACKAGE			
		PLASTIC SMALL OUTLINE (D, NS)	PLASTIC SHRINK SMALL OUTLINE (DB)	PLASTIC DIP (N)	PLASTIC THIN SHRINK SMALL OUTLINE (PW)
0°C to 70°C	10 mV	MC3403D MC3403NS	MC3403DB	MC3403N	MC3403PW
–40°C to 85°C	8 mV	MC3303D	—	MC3303N	MC3303PW

The D package is available taped and reeled. Add R suffix to the device type (e.g., MC3403DR). The DB, NS, and PW packages are only available taped and reeled.

logic diagram (each amplifier)



schematic (each amplifier)



Component values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (see Note 1): V_{CC+}	18 V
$V_{CC–}$	–18 V
Supply voltage, V_{CC+} with respect to $V_{CC–}$	36 V
Differential input voltage (see Note 2)	±36 V
Input voltage (see Notes 1 and 3)	±18 V
Package thermal impedance, θ_{JA} (see Note 4): D package	86°C/W
DB package	96°C/W
N package	80°C/W
NS package	76°C/W
PW package	113°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. These voltage values are with respect to the midpoint between V_{CC+} and $V_{CC–}$.
2. Differential voltages are at IN+ with respect to IN–.
3. Neither input must ever be more positive than V_{CC+} or more negative than $V_{CC–}$.
4. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	MAX	UNIT
V_{CC}	Supply voltage		5	30	V
	Dual-supply voltage	V_{CC+}	2.5	15	V
		V_{CC-}	–2.5	–15	V
T_A	Operating free-air temperature	MC3303	–40	85	°C
		MC3403	0	70	

electrical characteristics at specified free-air temperature, V_{CC+} = 14 V, V_{CC-} = 0 V for MC3303, $V_{CC\pm}$ = ±15 V for MC3403 (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MC3303			MC3403			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	See Note 5	25°C		2	8		2	10	mV
			Full range			10			12	
$\alpha_{V_{IO}}$	Temperature coefficient of input offset voltage	See Note 5	Full range		10			10		µV/°C
I_{IO}	Input offset current	See Note 5	25°C		30	75		30	50	nA
			Full range			250			200	
$\alpha_{I_{IO}}$	Temperature coefficient of input offset current	See Note 5	Full range		50			50		pA/C
I_{IB}	Input bias current	See Note 5	25°C		–0.2	–0.5		–0.2	–0.5	µA
			Full range			–1			–0.8	
V_{ICR}	Common-mode input voltage range‡		25°C	V_{CC-} to 12	V_{CC-} to 12.5		V_{CC-} to 13	V_{CC-} to 13.5		V
V_{OM}	Peak output voltage swing	R_L = 10 kΩ	25°C	12	12.5		±12	±13.5		V
		R_L = 2 kΩ	25°C	10	12		±10	±13		
		R_L = 2 kΩ	Full range	10			±10			
A_{VD}	Large-signal differential voltage amplification	V_O = ±10 V, R_L = 2 kΩ	25°C	20	200		20	200		V/mV
			Full range	15			15			
B_{OM}	Maximum-output-swing bandwidth	V_{OPP} = 20 V, A_{VD} = 1, THD ≤ 5%, R_L = 2 kΩ	25°C		9			9		kHz
B_1	Unity-gain bandwidth	V_O = 50 mV, R_L = 10 kΩ	25°C		1			1		MHz
ϕ_m	Phase margin	C_L = 200 pF, R_L = 2 kΩ	25°C		60°			60°		
r_i	Input resistance	f = 20 Hz	25°C	0.3	1		0.3	1		MΩ
r_o	Output resistance	f = 20 Hz	25°C		75			75		Ω
CMRR	Common-mode rejection ratio	V_{IC} = V_{ICR}min	25°C	70	90		70	90		dB
k_{SVS}	Supply voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC}$)	$V_{CC\pm}$ = ±2.5 to ±15 V	25°C		30	150		30	150	µV/V
I_{OS}	Short-circuit output current§		25°C	±10	±30	±45	±10	±30	±45	mA
I_{CC}	Total supply current	No load, See Note 5	25°C		2.8	7		2.8	7	mA

† All characteristics are measured under open-loop conditions with zero common-mode voltage unless otherwise specified. Full range for T_A is –40°C to 85°C for MC3303, and 0°C to 70°C for MC3403.

‡ The V_{ICR} limits are linked directly, volt-for-volt, to supply voltage; the positive limit is 2 V less than V_{CC+}.

§ Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.

NOTE 5: V_{IO}, I_{IO}, I_{IB}, and I_{CC} are defined at V_O = 0 for MC3403 and V_O = 7 V for MC3303.

electrical characteristics, V_{CC+} = 5 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	MC3303			MC3403			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_O = 2.5 V			10		2	10	mV
I_{IO}	Input offset current	V_O = 2.5 V			75		30	50	nA
I_{IB}	Input bias current	V_O = 2.5 V			–0.5		–0.2	–0.5	µA
V_{OM}	Peak output voltage swing‡	R_L = 10 kΩ	3.3	3.5		3.3	3.5		V
		R_L = 10 kΩ, V_{CC+} = 5 V to 30 V	V_{CC+} – 1.7			V_{CC+} – 1.7			
A_{VD}	Large-signal differential voltage amplification	V_O = 1.7 V to 3.3 V, R_L = 2 kΩ	20	200		20	200		V/mV
k_{SVS}	Supply-voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC\pm}$)	$V_{CC\pm}$ = ±2.5 V to ±15 V			150			150	µV/V
I_{CC}	Supply current	V_O = 2.5 V, No load		2.5	7		2.5	7	mA
V_{O1}/V_{O2}	Crosstalk attenuation	f = 1 kHz to 20 kHz		120			120		dB

† All characteristics are measured under open-loop conditions with zero common-mode input voltage unless otherwise specified.
‡ Output will swing essentially to ground.

operating characteristics, V_{CC+} = 14 V, V_{CC-} = 0 V for MC3303, $V_{CC\pm}$ = ±15 V for MC3403, T_A = 25°C, A_{VD} = 1 (unless otherwise noted)

PARAMETER		TEST CONDITIONS				TYP	UNIT
SR	Slew rate at unity gain	V_I = ±10 V,	C_L = 100 pF,	R_L = 2 kΩ,	See Figure 1	0.6	V/µs
t_r	Rise time	ΔV_O = 50 mV,	C_L = 100 pF,	R_L = 10 kΩ,	See Figure 1	0.35	µs
t_f	Fall time	ΔV_O = 50 mV,	C_L = 100 pF,	R_L = 10 kΩ,	See Figure 1	0.35	µs
	Overshoot factor	ΔV_O = 50 mV,	C_L = 100 pF,	R_L = 10 kΩ,	See Figure 1	20	%
	Crossover distortion	$V_{I(PP)}$ = 30 mV,	V_{OPP} = 2 V,	f = 10 kHz		1	%

PARAMETER MEASUREMENT INFORMATION

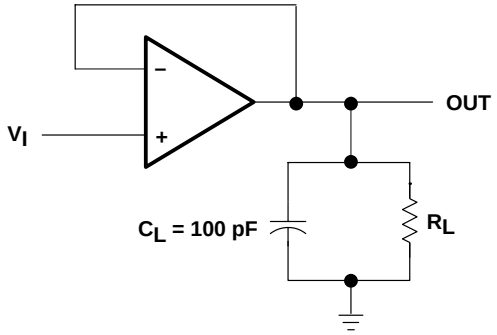


Figure 1. Unity-Gain Amplifier

TYPICAL CHARACTERISTICS†

MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE
vs
SUPPLY VOLTAGE

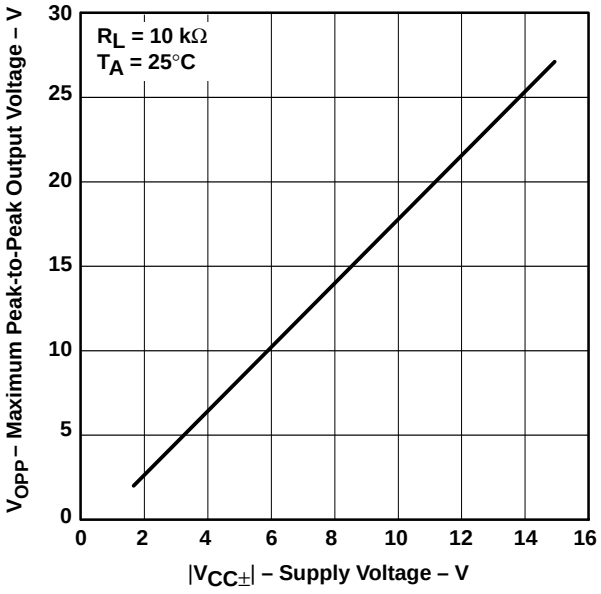


Figure 2

MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE
vs
FREQUENCY

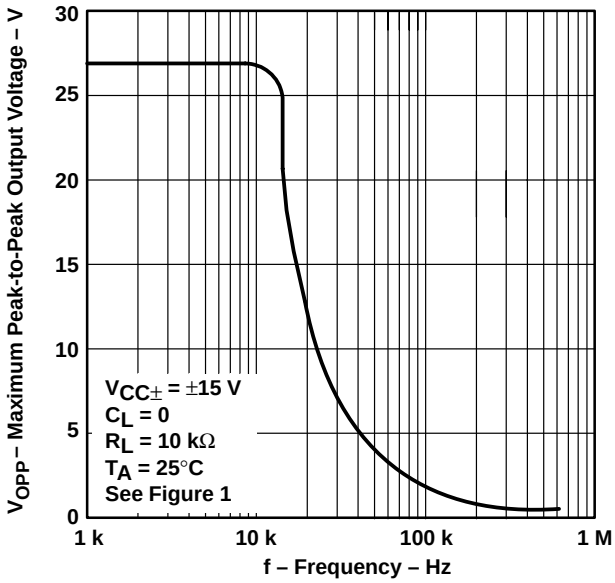


Figure 3

LARGE-SIGNAL
DIFFERENTIAL VOLTAGE AMPLIFICATION
vs
FREQUENCY

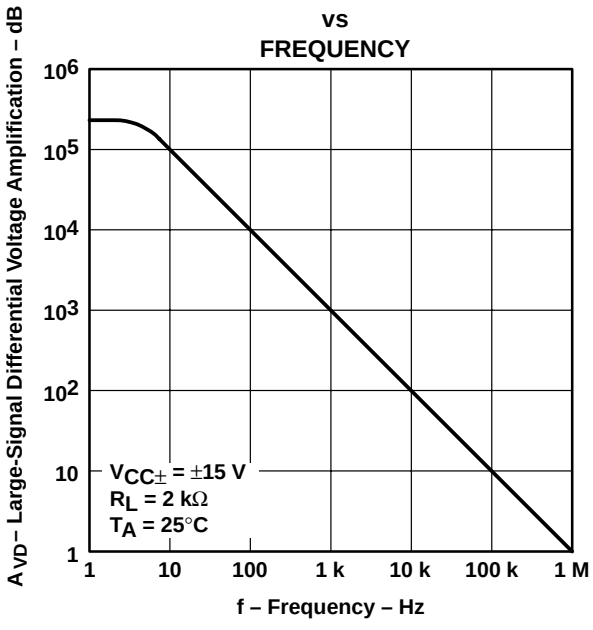


Figure 4

VOLTAGE-FOLLOWER
LARGE-SIGNAL PULSE RESPONSE

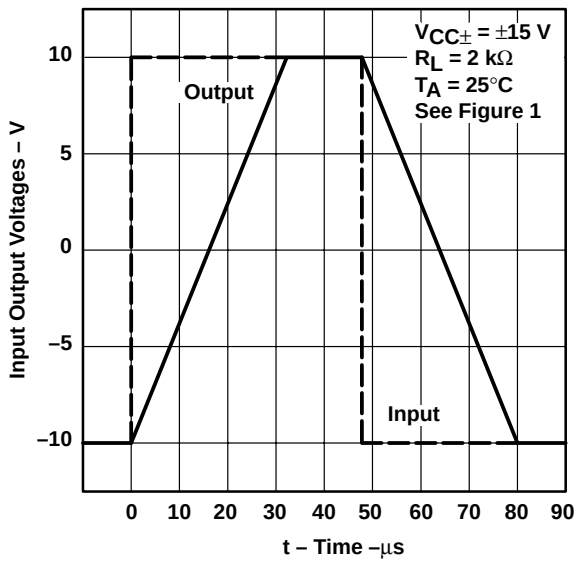


Figure 5

† Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

TYPICAL CHARACTERISTICS†

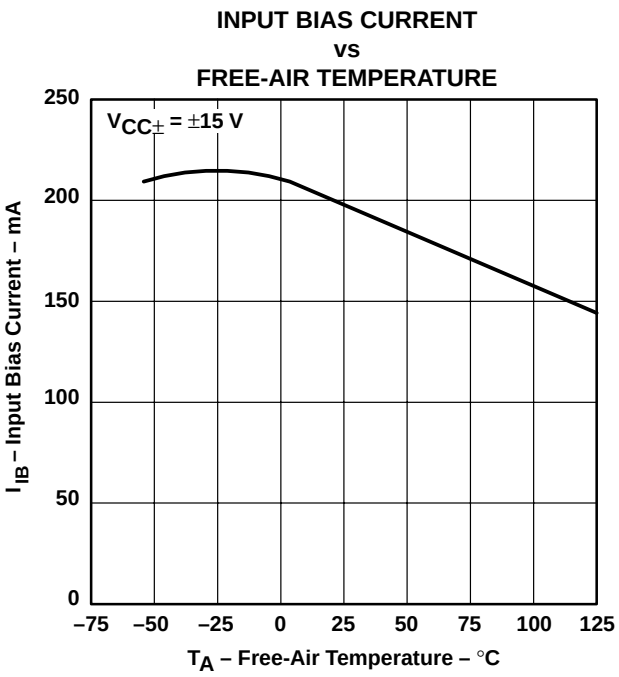


Figure 6

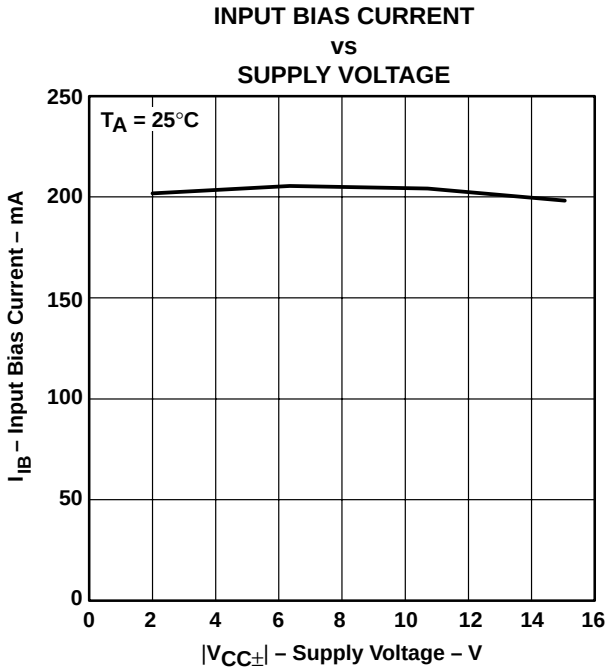


Figure 7

† Operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MC3303D	Obsolete	Production	SOIC (D) | 14	-	-	Call TI	Call TI	-40 to 85	MC3303
MC3303DR	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU | NIPDAU	Level-1-260C-UNLIM	-40 to 85	MC3303
MC3303DR.A	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MC3303
MC3303N	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	MC3303N
MC3303N.A	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	MC3303N
MC3303PW	Obsolete	Production	TSSOP (PW) | 14	-	-	Call TI	Call TI	-40 to 85	M3303
MC3303PWR	Active	Production	TSSOP (PW) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	M3303
MC3303PWR.A	Active	Production	TSSOP (PW) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	M3303
MC3403D	Obsolete	Production	SOIC (D) | 14	-	-	Call TI	Call TI	0 to 70	MC3403
MC3403DR	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3403
MC3403DR.A	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3403
MC3403N	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	MC3403N
MC3403N.A	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	MC3403N
MC3403NSR	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3403
MC3403NSR.A	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3403
MC3403PWR	Obsolete	Production	TSSOP (PW) | 14	-	-	Call TI	Call TI	0 to 70	M3403

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

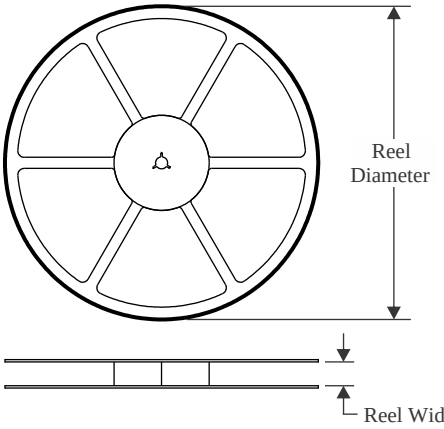
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

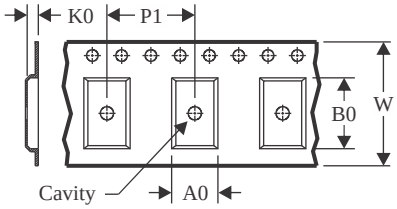
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

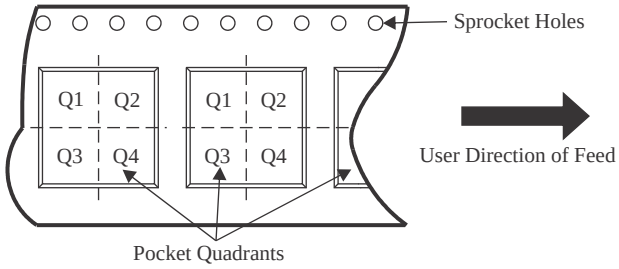


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

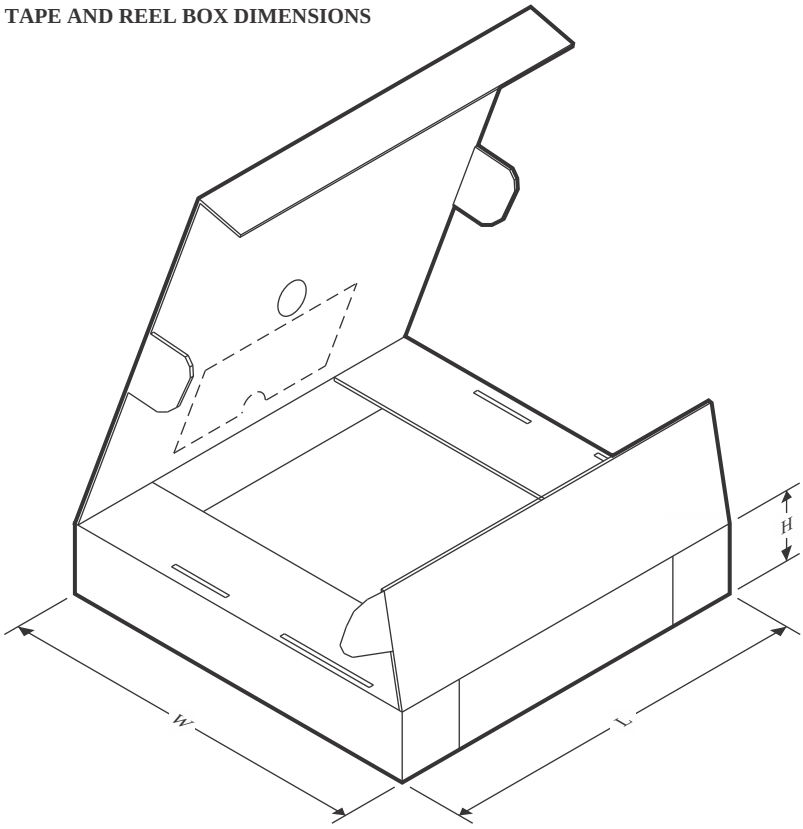
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MC3303DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
MC3303PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
MC3303PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
MC3403DR	SOIC	D	14	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
MC3403DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
MC3403NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

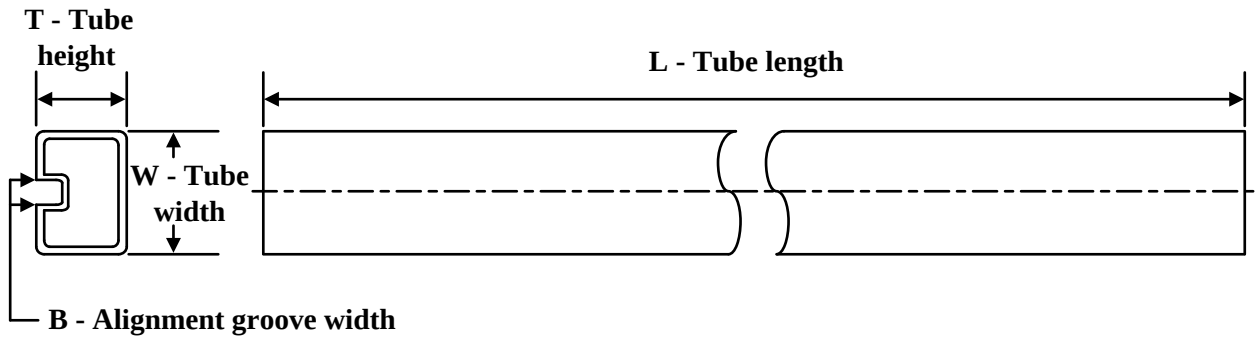
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

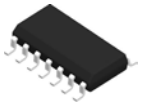
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MC3303DR	SOIC	D	14	2500	356.0	356.0	35.0
MC3303PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
MC3303PWR	TSSOP	PW	14	2000	353.0	353.0	32.0
MC3403DR	SOIC	D	14	2500	340.5	336.1	25.0
MC3403DR	SOIC	D	14	2500	353.0	353.0	32.0
MC3403NSR	SOP	NS	14	2000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
MC3303N	N	PDIP	14	25	506	13.97	11230	4.32
MC3303N	N	PDIP	14	25	506	13.97	11230	4.32
MC3303N.A	N	PDIP	14	25	506	13.97	11230	4.32
MC3303N.A	N	PDIP	14	25	506	13.97	11230	4.32
MC3403N	N	PDIP	14	25	506	13.97	11230	4.32
MC3403N	N	PDIP	14	25	506	13.97	11230	4.32
MC3403N.A	N	PDIP	14	25	506	13.97	11230	4.32
MC3403N.A	N	PDIP	14	25	506	13.97	11230	4.32

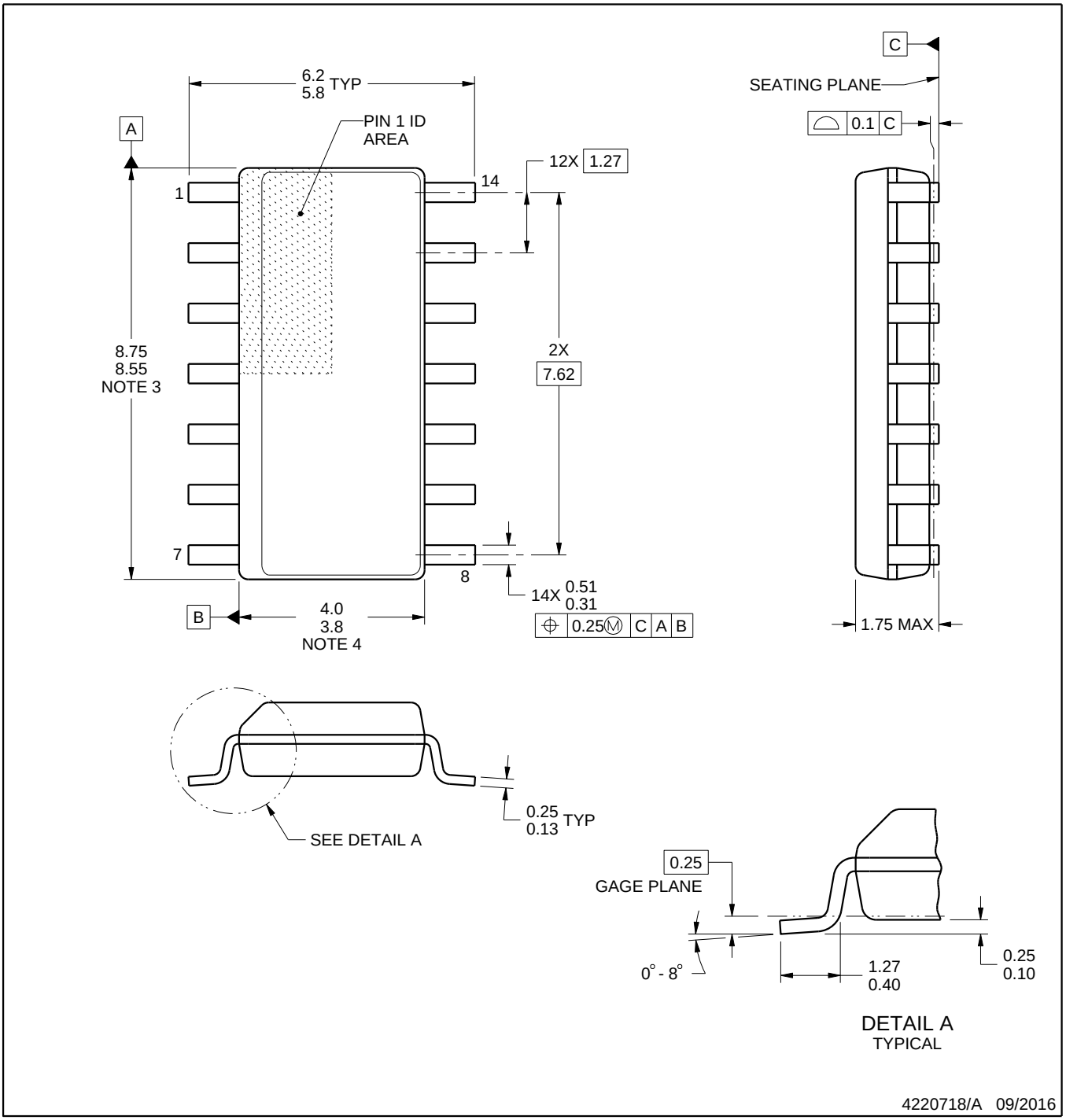


PACKAGE OUTLINE

D0014A

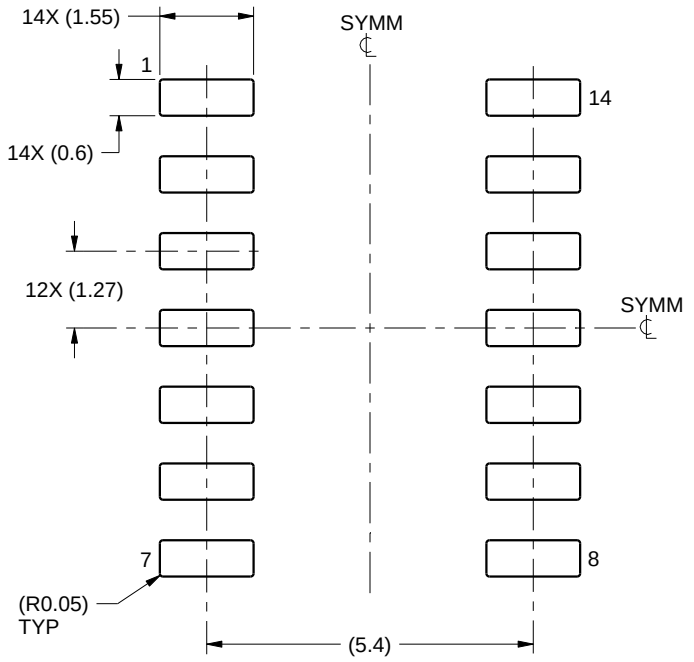
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

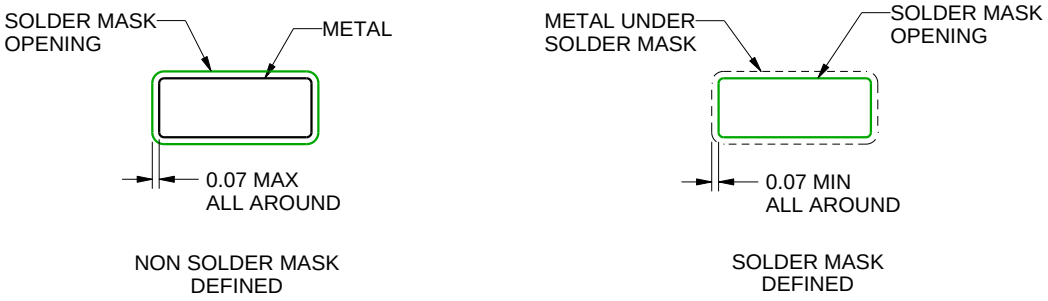


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

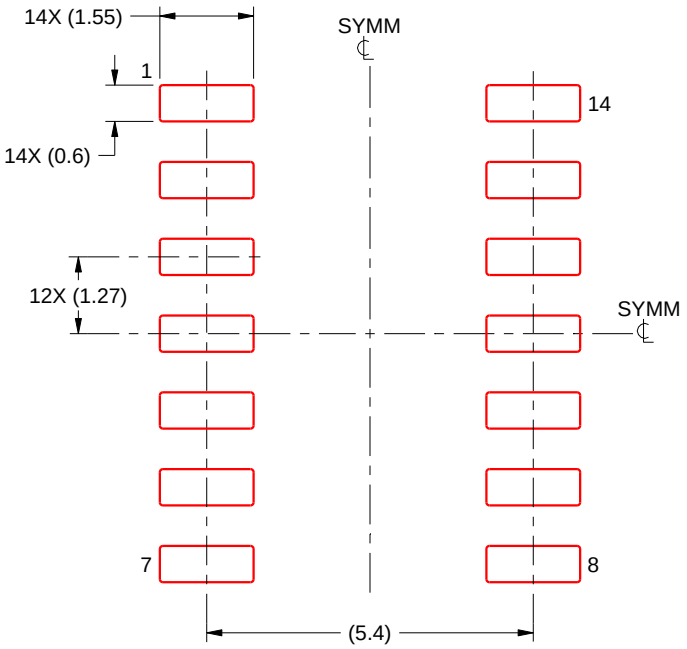
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

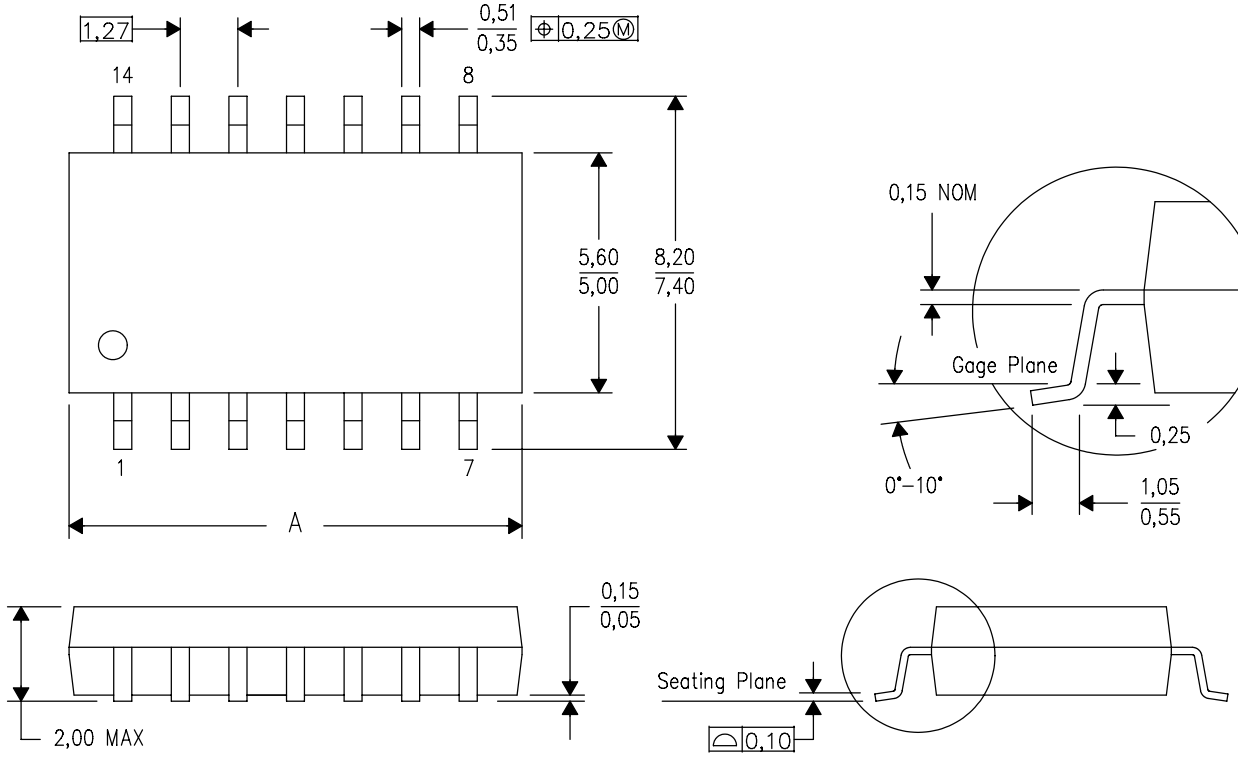
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

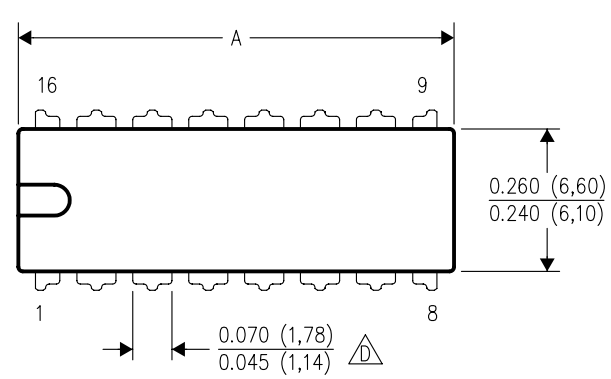
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

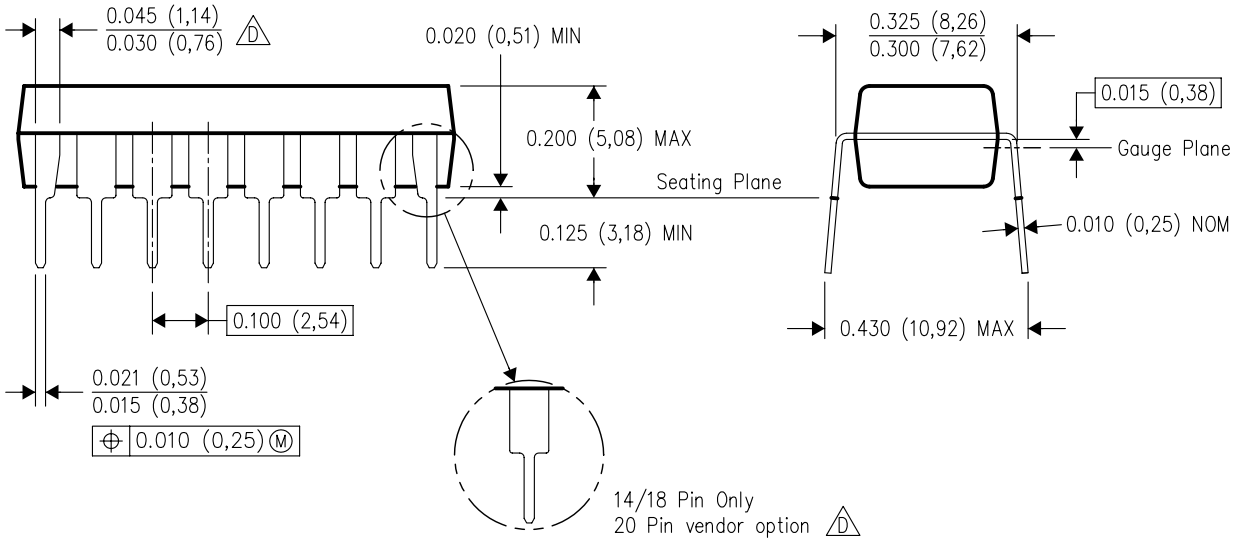
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

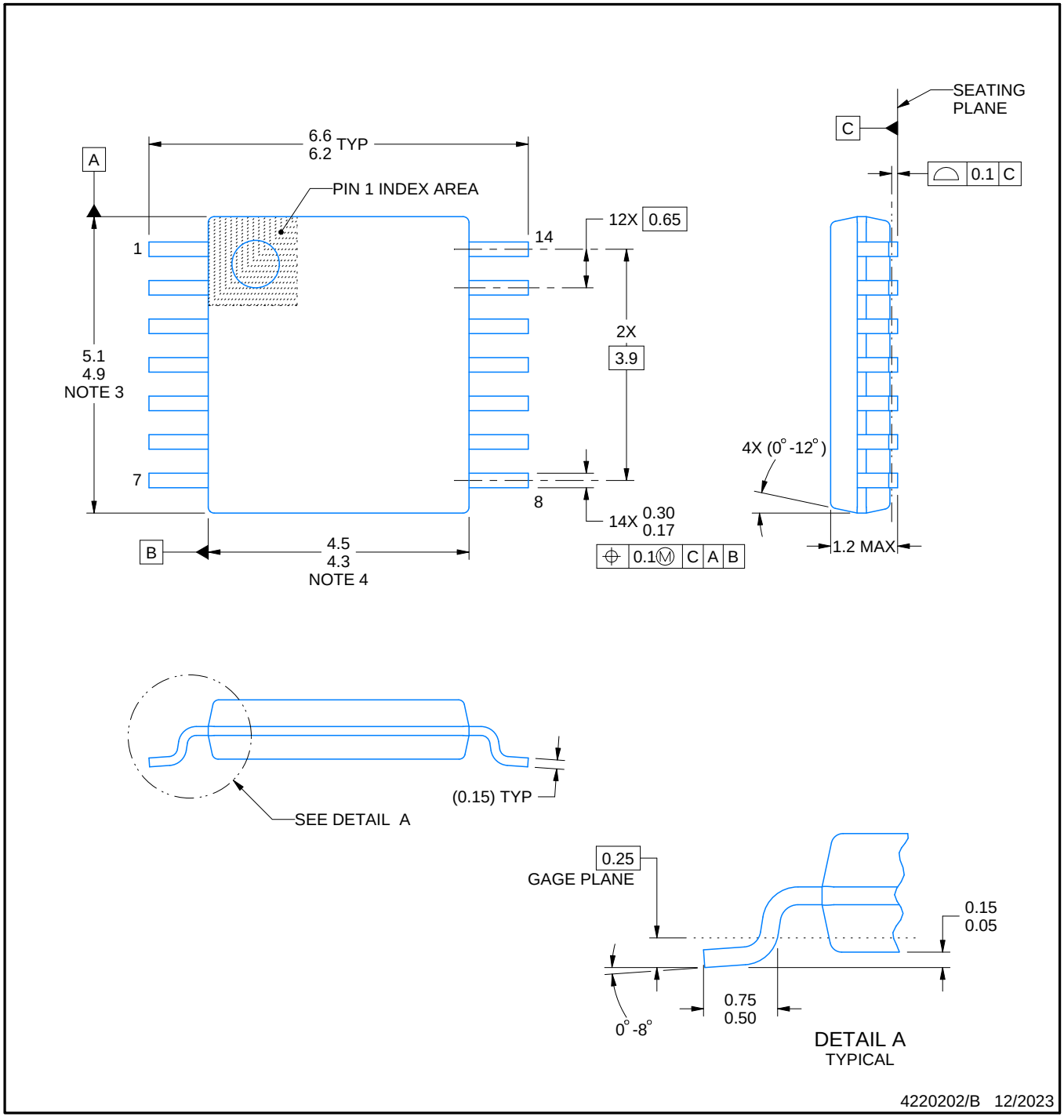
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

PACKAGE OUTLINE

PW0014A

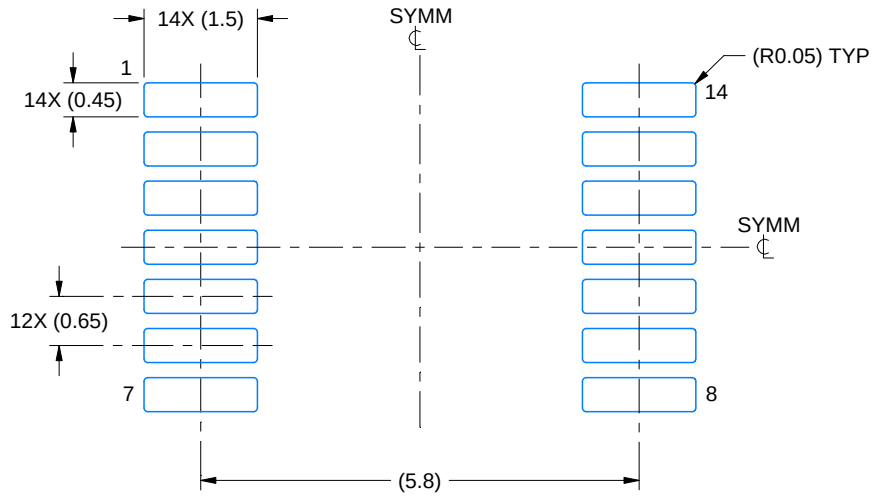
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

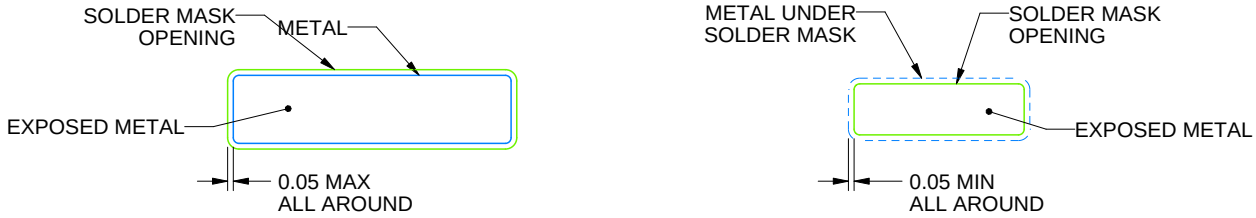


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

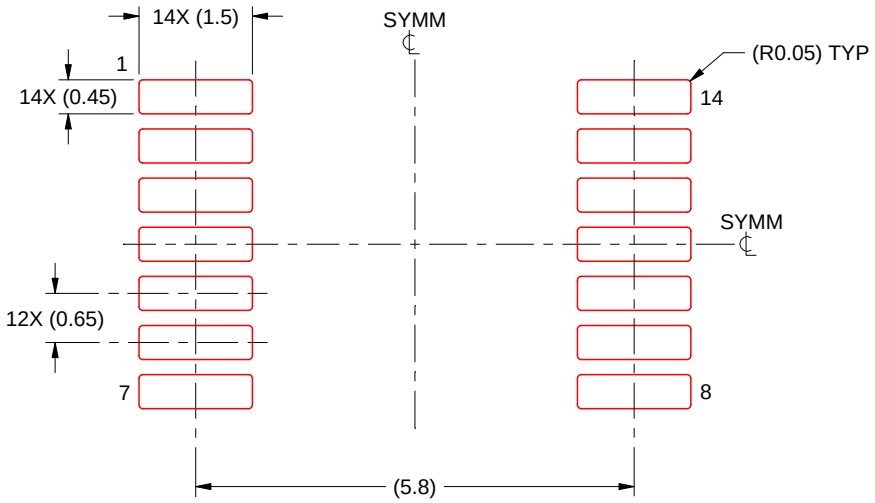


SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265